

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
IRVINE SENSORS CORPORATION	03/16/2009
RECEIVING PARTY DATA	
Name:	APROLASE DEVELOPMENT CO., LLC
Street Address:	2711 Centerville Road
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	06403004
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ASSIGNMENT OF RIGHTS IN CERTAIN ASSETS

For good and valuable consideration, the receipt of which is hereby acknowledged, Irvine Sensors Corporation, a Delaware corporation, with an office at 3001 Redhill Ave., Bldg. 4, Suite 108, Costa Mesa, CA 92672 ("**Assignor**"), does hereby sell, assign, transfer, and convey unto Aproz Development Co., LLC, a Delaware limited liability company, having an address at 2711 Centerville Road, Suite 400, Wilmington, DE 19808 ("**Assignee**"), or its designees, the right, title, and interest in and to any and all of the following provisional patent applications, patent applications, patents, and other governmental grants or issuances of any kind (the "**Certain Assets**"):

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
PCT/US00/029448	WO	10/25/2000	SYSTEM AND METHODS FOR PRODUCING HIGH RESOLUTION IMAGES FROM A VIDEO SEQUENCE OF LOWER RESOLUTION IMAGES CARLSON RANDOLPH S; ARNOLD JACK L; FELDMUS VALENTIN G
PCT/US92/005348	WO	6/24/1992	Fabricating electronic circuitry unit containing stacked IC layers having lead rerouting Go, Tiong C.(deceased,); Minahan, Joseph A.; Shanken, Stuart N.
PCT/US03/004462	WO	5/5/1993	Non-conductive end layer for integrated stack of IC chips Miyake, Michael K.
PCT/US99/013171	WO	6/10/1999	IC stack utilizing flexible circuits with BGA contacts Eide, Floyd K.
PCT/US06/008920	WO	3/10/2006	Method for making a neo-layer comprising embedded discrete components He, Sambo
PCT/US01/031583	WO	10/9/2001	High speed switching module comprised of stacked layers incorporating T-connect structures John C. Carson; Volkan H. Orguz
PCT/US02/002276	WO	1/25/2002	A stackable microcircuit layer formed from a plastic encapsulated microcircuit and method of making the same Albert, Douglas M.; Gann, Keith D.
PCT/US02/006848	WO	3/4/2002	Retro-reflector warm stop for uncooled thermal imaging cameras and method of using the same Kaufman, Charles S.

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
PCT/US02/022617	WO	7/16/2002	Wearable biomonitor with flexible thinned integrated circuit Ogzuz, Volkhan H; Khashayar, Abbas
PCT/US02/028628	WO	9/9/2002	Stacking of multilayer modules Yamaguchi, James Satsuo; Pepe, Angel Antonio; Ozguz, Volkan H.; Camien, Andrew Nelson
PCT/US02/034339	WO	10/25/2002	Stackable layers containing encapsulated integrated circuit chips with one or more overlying interconnect layers and a method of making the same Pepe, Angel Antonio; Yamaguchi, James Satsuo
PCT/US02/19779	WO	6/24/2002	Video event capture, storage and processing method and apparatus Randolph S. Carlson
PCT/US03/009190	WO	9/27/1993	Fabrication of dense parallel solder bump connections Pepe, Angel A.; Reinker, David M.; Minahan, Joseph A.
PCT/US03/013569	WO	4/22/2003	Method and apparatus for connecting vertically stacked integrated circuit chips Gann, Keith D.; Albert, Douglas M.
PCT/US03/024706	WO	08/08/2003	Stackable layers containing ball grid array packages Eide, Floyd K.
PCT/US83/01142	WO	7/25/1983	Multiplexer circuitry for high density analog signals
PCT/US88/003084	WO	9/8/1988	Bonding of aligned conductive bumps on adjacent surfaces Go, Tiong C.
PCT/US92/000780	WO	1/29/1992	Hardware for electronic neural network Carson, John C.
PCT/US92/003705	WO	6/28/1990	Fabricating electronic circuitry unit containing stacked IC layers having lead rerouting Go, Tiong C.(deceased,); Minahan, Joseph A.; Shanken, Stuart N.

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
PCT/US93/009470	WO	10/5/1993	Apparatus and system for controllably varying image resolution to reduce data output Arnold, Jack
PCT/US93/011601	WO	12/1/1993	Module comprising IC memory stack dedicated to and structurally combined with an IC microprocessor chip Carson, John C.; Indin, Ronald J.; Shanken, Stuart N.
PCT/US93/012268	WO	12/16/1993	Fabricating stacks of IC chips by segmenting a larger stack MINIHAN JOSEPH A; PEPE ANGEL A
PCT/US94/004322	WO	4/19/1994	Electronic module comprising a stack of IC chips Carson, John C.; Some, Raphael R.
PCT/US94/009186	WO	8/12/1994	Stack of IC chips as substitute for single IC chip Ludwig, David E.; Saunders, Christ H.; Some, Raphael R.; Stuart, John J.
PCT/US95/002851	WO	3/7/1995	3D stack of IC chips having leads reached by vias through passivation covering access plane Johnson, Tony K.
PCT/US95/012378	WO	9/27/1995	Infrared wireless communication between electronic system components DeCaro, Robert; Saunders, Christ H.; Maeding, Dale
PCT/US96/000746	WO	1/22/1996	Stackable modules and multimodular assemblies Carson, John C.; DeCaro, Robert E.; Hsu, Ying; Miyake, Michael K.
PCT/US96/014610	WO	9/11/1996	SENSING AND SELECTING OBSERVED EVENTS FOR SIGNAL PROCESSING SAUNDERS CHRIST H
PCT/US98/021798	WO	10/14/1998	Multi-element micro gyro Hsu, Ying Wen
PCT/US98/023929	WO	11/10/1998	Method for thinning semiconductor wafers with circuits and wafers made by the same Albert, Douglas; Ogzuz Volkhan H

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
PCT/US99/001734	WO	3/23/1990	Analog to digital conversion incorporated in Z-technology module Wall, Llewellyn E.
PCT/US99/004211	WO	2/25/1999	STACKING LAYERS CONTAINING ENCLOSED IC CHIPS EIDE FLOYD
PCT/US99/031124	WO	12/30/1999	Neural processing module with input architectures that make maximal use of a weighted synapse array Carson, John C.; Saunders, Christ H.
07/329,003	US	3/27/1989	Analog to digital conversion on multiple channel IC chips Wall, Llewellyn E.
07/377,241	US	7/7/1989	Inventorship not available
07/884,719	US	5/15/1992	Method for fabricating stacks of IC chips by segmenting a larger stack Minahan, Joseph A.; Pepe, Angel A.
07/884660	US	5/15/1992	Non-conductive end layer for integrated stack of IC chips Miyake, Michael K.
07/955461	US	10/2/1992	Fabrication of dense parallel solder bump connections Joseph Minahan
08/052,475	US	4/23/1993	Electronic module comprising a stack of IC chips each interacting with an IC chip secured to the stack face Carson, John C.; Some, Raphael R.
08/106,909	US	8/13/1993	Inventorship not available
08/213,149	US	3/15/1994	3D stack of IC chips having leads reached by vias through passivation covering access plane Johnson, Tony K.
08/870,812	US	6/6/1997	Multi-element micro gyro Hsu, Ying W.; Reeds, III, John W.; Saunders, Christ H.
08/943,305	US	10/14/1997	Multi-element micro gyro Hsu, Ying W.; Reeds, III, John W.; Saunders, Christ H.

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
09/190,378	US	11/10/1998	Method for thinning semiconductor wafers with circuits and wafers made by the same Albert, Douglas
09/770,864	US	1/26/2001	Method of making a stackable microcircuit layer from a plastic encapsulated microcircuit Douglas M. Albert; Keith D. Gann
10/197,006	US	7/16/2002	Wearable biomonitor with flexible thinned integrated circuit Ogzuz, Volkhan H; Khashayar, Abbas
10/663,371	US		Stacked microelectronic module with vertical interconnect vias Ogzuz, Volkhan H;
10/805,849	US	3/22/2004	Three-dimensional imaging device incorporating stacked layers containing microelectronic circuits David E. Ludwig; John V. Kennedy; Christian Krutzik
11/003,429	US	12/6/2004	Wearable biomonitor with flexible thinned integrated circuit Ogzuz, Volkhan H; Khashayar, Abbas
60/036,759	US	1/28/1997	Multi-element micro gyro Hsu, Ying W.; Reeds, III, John W.; Saunders, Christ H.
60/049,025	US	6/9/1997	Stacking layers containing enclosed IC chips Eide, Floyd K.
60/049,026	US	6/9/1997	Stacking layers containing enclosed IC chips Eide, Floyd K.
60/049,582	US	6/13/1997	IC stack utilizing BGA contacts Eide, Floyd K.
60/065,088	US		
60/238,797	US	10/6/2000	High speed data switch with traverse-mated stacks containing superconducting electronics John Carson
60/274,120	US		
60/305,353	US		Biomonitor device Ogzuz, Volkhan H
60/346,494	US	1/9/2002	Low cost miniature computer and methods for making same Gann, Keith

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
60/348,852	US	1/17/2002	Field programmable gate array structure incorporating high density support circuitry and method for making same Ozguz, Volkan H.;
60/354,442	US	2/7/2002	BGA layer and assembly and method for making same Eide, Floyd K.
60/355,955	US	2/12/2002	Stacked BGA assembly Eide, Floyd K.
60/394,167	US	7/8/2002	Cryopump piston position tracking using an encoder Sapir, Itzhak
60/410,895	US		Wearable biomonitor with flexible thinned integrated circuit Ogzuz, Volkhan H; Khashayar, Abbas
60/424,022	US		NEO-wafers and NEO-chips, device and method Sambo S. He
60/424,025	US	11/6/2002	Creating wafers from singulated die Stern, Jonathan Michael
60/462,677	US	3/28/2003	High-speed transmitter and receiver incorporating three-dimensional readout electronic module David E. Ludwig;
60/546,598	US	2/20/2004	BGA-scale stacks comprised of thin small outline packages and method for making the same Gann Keith; William E. Boyd
60/617,356	US	10/8/2004	Anti-tamper module Volkan H. Ozguz; John Leon
60/652,777	US	2/14/2005	Stacked ball grid array package module utilizing one or more interposer layers William E. Boyd; Daniel Michaels
60/678,618	US	5/5/2005	GPS incorporating low power real time clock circuitry Itzhak Sapir
60/684,372	US	5/26/2005	Stackable layers of encapsulated integrated circuit chips interconnected with prefabricated via structures Volkan Ozguz; Jonathan Stern

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
60/710,717	US	8/24/2005	Surface trenched stackable layers Keith Gann; Douglas N. Albert
60/711,375	US	8/26/2005	High density interconnect scheme for stacked electronic modules John V. Kennedy
60/711,376	US	8/26/2005	MEMS cooling device Itzhak Sapir
60/758,922	US	1/17/2006	Absolute pressure sensor Sapir, Itzhak
60/628,742	US	11/18/2004	Interface optimization of high density interconnects Stewart Clark
60/617,426	US	10/8/2004	Interface optimization of high density interconnects Stewart Clark
RE33331 (07/336,017)	US	9/11/1990 (4/10/1989)	Multiplexer circuitry for high density analog signals Inventorship not available
4,490,626 (06/403,004)	US	12/25/1984 (7/29/1982)	Multiplexer circuitry for high density analog signals Carlson, Randolph S.
4,912,545 (07/097,797)	US	3/27/1990 (9/16/1987)	Bonding of aligned conductive bumps on adjacent surfaces Go, Tiong C.
4,983,533 (07/114,415)	US	1/8/1991 (10/28/1987)	High-density electronic modules - process and product Go, Tiong C.
4,290,844 (06/015070)	US	9/22/1981 (2/26/1979)	Focal plane photo-detector mosaic array fabrication Rotolante, Ralph A.; Koehler, Toivo
4,304,624 (05/855242)	US	12/8/1981 (11/28/1977)	Method of fabricating a multi-layer structure for detector array module Carson, John C.; Dahlgren, Paul F.
4,352,715 (06/206993)	US	10/5/1982 (11/17/1980)	Detector array module fabrication Carson, John C.; Dahlgren, Paul F.
4,354,107 (06/206994)	US	10/12/1982 (11/14/1980)	Detector array module-structure and fabrication Carson, John C.; Dahlgren, Paul F.

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
4,403,238 (06/213933)	US	9/6/1983 (12/8/1980)	Detector array focal plane configuration Clark, Stewart A.
4,449,044 (06/262296)	US	5/15/1984 (5/11/1981)	Focal plane photo-detector mosaic array apparatus Rotolante, Ralph A.; Koehler, Toivo
4,525,921 (06/517221)	US	7/2/1985 (7/25/1983)	High-density electronic processing package-structure and fabrication Carson, John C.; Clark, Stewart A.
4,551,629 (06/572802)	US	11/5/1985 (1/23/1984)	Detector array module-structure and fabrication Carson, John C.; Clark, Stewart A.
4,555,623 (06/558099)	US	11/26/1985 (12/5/1983)	Pre-amplifier in focal plane detector array Bridgewater, Walter F.; De Caro, Robert E.; Larson, Roger; Wall, Llewellyn E.
4,596,948 (06/661727)	US	6/24/1986 (10/17/1984)	Constant current source for integrated circuits Wall, Llewellyn E.
4,617,160 (06/674096)	US	10/14/1986 (11/23/1984)	Method for fabricating modules comprising uniformly stacked, aligned circuit-carrying layers Belanger, Robert J.; Bisignano, Alan G.
4,646,128 (06/720902)	US	2/24/1987 (4/8/1985)	High-density electronic processing package--structure and fabrication Carson, John C.; Clark, Stewart A.
4,672,737 (06/761889)	US	6/16/1987 (8/2/1985)	Detector array module fabrication process Carson, John C.; Clark, Stewart A.
4,675,532 (06/795988)	US	6/23/1987 (11/6/1985)	Combined staring and scanning photodetector sensing system having both temporal and spatial filter in Carson, John C.
4,704,319 (06/842159)	US	11/3/1987 (3/21/1986)	Apparatus and method for fabricating modules comprising stacked circuit-carrying layers Belanger, Robert J.; Bisignano, Alan G.

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
4,706,166 (06/856835)	US	11/10/1987 (4/25/1986)	High-density electronic modules-- process and product Go, Tiong C.
4,764,846 (07/000562)	US	8/16/1988 (1/5/1987)	High density electronic package comprising stacked sub-modules Go, Tiong C.
4,779,005 (07/048551)	US	10/18/1988 (5/11/1987)	Multiple detector viewing of pixels using parallel time delay and integration circuitry Arnold, Jack L.
4,791,286 (07/042686)	US	12/13/1988 (4/27/1987)	Pre-amplifier in focal plane detector array Wall, Llewellyn E.
4,806,761 (07/023644)	US	2/21/1989 (3/9/1987)	Thermal imager incorporating electronics module having focal plane sensor mosaic Carson, John C.; Clark, Stewart A.
4,912,545 (07/097797)	US	3/27/1990 (9/16/1987)	Bonding of aligned conductive bumps on adjacent surfaces Go, Tiong C.
5,701,233 (08/376,799)	US	12/23/1997 (1/23/1995)	Stackable modules and multimodular assemblies Carson, John C.; DeCaro, Robert E.; Hsu, Ying; Miyake, Michael K.
5,745,631 (08/592,691)	US	4/28/1998 (1/26/1996)	Self-aligning optical beam system Reinker, David M.
NL0511218 (NL90917886.5)	NL	3/12/1997 (6/28/1990)	Fabricating electronic circuitry unit containing stacked IC layers having lead rerouting Go, Tiong C.(deceased,); Minahan, Joseph A.; Shanken, Stuart N.
JP06-0515293	JP	12/16/1993	Inventorship not available
JP97-0513369	JP	9/27/1995	Infrared wireless communication between electronic system components DeCaro, Robert; Saunders, Christ H.; Maeding, Dale
JP02-0506137	JP	3/23/1990	Inventorship not available
JP04-0505734	JP	1/29/1992	Hardware for electronic neural network Carson, John C.

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
JP58-502699	JP	7/25/1983	Inventorship not available
PCT/US98/021798	WO	10/14/1998	Multi-element micro gyroHsu, Ying Wen
FR0511218 (FR90917886.5)	FR	3/12/1997 (6/28/1990)	Fabricating electronic circuitry unit containing stacked IC layers having lead rerouting Go, Tiong C.(deceased.); Minahan, Joseph A.; Shanken, Stuart N.
EP0116072 (EP83902618.4)	EP	10/11/1989 (7/25/1983)	Multiplexer circuitry for high density analog signals
EP01979633.3	EP	10/9/2001	High speed multi-stage stacked layer switch John C. Carson; Volkan H. Orguz
EP02797722.2	EP	3/4/2002	Retro-reflector warm stop for uncooled thermal imaging cameras and method of using the same Kaufman, Charles S.
EP0511218 (EP90917886.5)	EP	3/12/1997 (6/28/1990)	Fabricating electronic circuitry unit containing stacked IC layers having lead rerouting Go, Tiong C.(deceased.); Minahan, Joseph A.; Shanken, Stuart N.
EP0570479 (EP92905662.0)	EP	10/10/2001 (1/29/1992)	Hardware for electronic neural network Carson, John C.
EP067087(EP94909418.9)	EP	(12/16/1993)	Fabricating stacks of IC chips by segmenting a larger stackMINIHAN JOSEPH A; PEPE ANGEL A
EP0683968 (EP94903352.6)	EP	10/24/2002 (12/1/1993)	Module comprising IC memory stack dedicated to and structurally combined with an IC microprocessor chip Carson, John C.; Indin, Ronald J.; Shanken, Stuart N.
EP0695494 (EP94915397.7)	EP	2/24/2001 (4/19/1994)	Electronic module comprising a stack of IC chips Carson, John C.; Some, Raphael R.
EP0713609 (EP94925876.8)	EP	5/7/2003 (8/12/1994)	Stack of IC chips as substitute for single IC chip Ludwig, David E.; Saunders, Christ H.; Some, Raphael R.; Stuart, John J.

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
EP90906503.9	EP	3/23/1990	Analog to digital conversion in Z-technology module Wall, Llewellyn E.
EP92916059.6	EP	6/24/1992	Fabricating electronic circuitry unit containing stacked IC layers having lead rerouting Go, Tiong C.(deceased.); Minahan, Joseph A.; Shanken, Stuart N.
EP93922760.9	EP	9/27/1993	Fabrication of dense parallel solder bump connections Pepe, Angel A.; Reinker, David M.; Minahan, Joseph A.
EP96902733.3	EP	1/22/1996	Stackable modules and multimodular assemblies Carson, John C.; DeCaro, Robert E.; Hsu, Ying; Miyake, Michael K.
EP98957755.6	EP	11/10/1998	Method for thinning semiconductor wafers with circuits and wafers made by the same Albert, Douglas; Ogzuz Volkhan H
EP98964683.1	EP	10/14/1998	Multi-element micro gyro Hsu, Ying Wen
DE0683968 (DE94903352.6)	DE	10/24/2002 (12/1/1993)	Module comprising IC memory stack dedicated to and structurally combined with an IC microprocessor chip Carson, John C.; Indin, Ronald J.; Shanken, Stuart N.
DE69030195 (DE69030195.2)	DE	3/12/1997 (6/28/1990)	Fabricating electronic circuitry unit containing stacked IC layers having lead rerouting Go, Tiong C.(deceased.); Minahan, Joseph A.; Shanken, Stuart N.
FR0116072 (FR83902618.4)	FR	7/25/1983	Multiplexer circuitry for high density analog signals Inventorship not available
DE0116072 (DE83902618.4)	DE	7/25/1983	Multiplexer circuitry for high density analog signals Inventorship not available
GB0116072 (GB83902618.4)	GB	7/25/1983	Multiplexer circuitry for high density analog signals Inventorship not available

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NL0116072 (NL83902618.4)	NL	7/25/1983	Multiplexer circuitry for high density analog signals Inventorship not available
SE0116072 (SE83902618.4)	SE	7/25/1983	Multiplexer circuitry for high density analog signals Inventorship not available
EP0596075 (EP93911250.4)	EP	8/22/2001 (5/5/1993)	Non-conductive end layer for integrated stack of IC chipsMiyake, Michael K.
EP1097467 (EP99928570.2)	EP	11/2/2006 (6/10/1993)	IC stack utilizing secondary leadframes Eide, Floyd K.
10/339,023	US	1/9/2003	Method for making stacked integrated circuits (ICs) using prepackaged partsKeith D. Gann
11/644,438	US	12/22/2006	Method for making stacked integrated circuits (ICs) using prepackaged parts Keith D. Gann
09/949,203	US	9/7/2001	Method of manufacturing multilayer modules James Satsuo Yamaguchi; Angel Antonio Pepe; Volkan H. Ozguz; Andrew Nelson Camien
EP1596433 (EP04394026.1)	EP	1/2/2008 (5/12/2004)	A method for creating neo-wafers from singulated integrated circuit die and a device made according to the method Stern, Jonathan Michael
TR1596433 (TR04394026.1)	TR	1/2/2008 (5/12/2004)	A method for creating neo-wafers from singulated integrated circuit die and a device made according to the method Stern, Jonathan Michael

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
IT1596433 (IT04394026.1)	IT	1/2/2008 (5/12/2004)	A method for creating neo-wafers from singulated integrated circuit die and a device made according to the method Stern, Jonathan Michael
IE1596433 (IE04394026.1)	IE	1/2/2008 (5/12/2004)	A method for creating neo-wafers from singulated integrated circuit die and a device made according to the method Stern, Jonathan Michael
EP05111589.7	EP	12/1/2005	BGA-scale stacks comprised of layers containing integrated circuit die and a method for making the same Gann Keith; William E. Boyd
11/302,480	US	12/12/2005	Neo-wafer device comprised of multiple singulated integrated circuit die Stern Jonathan
JP2098125 (JP63-501172)	JP	10/20/1987	High-density electronic modules, process and product Go, Tiong C.
DE6933329	DE	12/16/1993	Method for fabricating stacks of IC chips by segmenting a larger stack Joseph A. Minahan
IT0676087	IT	12/16/1993	Method for fabricating stacks of IC chips by segmenting a larger stack Joseph A. Minahan
NL0676087	NL	12/16/1993	Method for fabricating stacks of IC chips by segmenting a larger stack Joseph A. Minahan
PCT/US99/023460	WO	10/6/1999	Multi-element micro gyro Ying W. Hsu

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
EP99951869.9	EP	10/6/1999	Multi-element micro gyro Ying W. Hsu
60/049,580	US	6/13/1997	IC stack utilizing secondary leadframes Floyd K. Eide
PCT/US99/013173	WO	06/10/1999	IC stack utilizing secondary leadframes Floyd K. Eide
DE69933873	DE	6/10/1999	IC stack utilizing secondary leadframes Floyd K. Eide
PCT/US02/006803	WO	3/4/2002	Method and apparatus for temperature compensation of an uncooled focal plane array Randolph S. Carson
EP02721271.1	EP	3/4/2002	Method and apparatus for temperature compensation of an uncooled focal plane array Randolph S. Carson
CY1596433	CY	5/12/2004	Method for creating neo-wafers from singulated integrated circuit die and a device made according to the method Jonathan Stern
EE1596433	EE	5/12/2004	Method for creating neo-wafers from singulated integrated circuit die and a device made according to the method Jonathan Stern
GR1596433	GR	5/12/2004	Method for creating neo-wafers from singulated integrated circuit die and a device made according to the method Jonathan Stern

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
HU1596433	HU	5/12/2004	Method for creating neo-wafers from singulated integrated circuit die and a device made according to the method Jonathan Stern
LU1596433	LU	5/12/2004	Method for creating neo-wafers from singulated integrated circuit die and a device made according to the method Jonathan Stern
11/302,480	US	12/12/2005	Neo-wafer device comprised of multiple singulated integrated circuit die Jonathan Stern
60/785,135	US	3/24/2006	Method for image jitter reduction in a multiplayer LADAR device John Kennedy
60/300,449	US	6/25/2001	Video event capture, storage and processing method and apparatus Randolph S. Carlson
PCT/US06/005754	WO	2/14/2006	Stacked ball grid array package module utilizing one or more interposer layers William E. Boyd
PCT/US96/005065	WO	4/11/1996	Dry adhesive joining of layers of electronic devices Angel A. Pepe
PCT/US88/000060	WO	1/4/1998	High density electronic package comprising stacked sub-modules Tiong C. Go
PCT/US00/041207	WO	10/16/2006	Highly configurable capacitive transducer interface circuit Christ Ying Hsu

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
PCT/US02/019452	WO	6/18/2002	Mems sensor with single central anchor and motion-limiting connection geometry John William Reeds III
PCT/US02/020290	WO	6/26/2002	Method of designing a flexure system for turning the modal response of a decoupled micromachined gyroscope and a gyroscope designed according to the method Michael J. Tracy
PCT/US01/08720	WO	3/19/2001	Method of canceling quadrature error in an angular rate sensor Ying Wen Hsu
06/187,787	US	9/16/1980	Detector array module-structure and fabrication John C. Carson
06/282,459	US	7/13/1981	Detector array module-structure and fabrication John C. Carson
60/159,832	US	10/15/1999	Universal capacitive interface circuit Christ Ying Hsu
06/721,040	US	4/8/1985	Thermal imager incorporating electronics module having focal plane sensor mosaic John C. Carson
60/190,271	US	3/17/2000	Method for canceling quadrature error in angular rate sensor Ying Wen Hsu
EP0340241	EP	1/4/1998	High density electronic package comprising stacked sub-modules Tiong C. Go

<u>Patent or Application No.</u>	<u>Country</u>	<u>Filing Date</u>	<u>Title of Patent and First Named Inventor</u>
DE3854814	DE	1/4/1998	High density electronic package comprising stacked sub-modules Tiong C. Go
FR0340241	FR	1/4/1998	High density electronic package comprising stacked sub-modules Tiong C. Go
GB0340241	GB	1/4/1998	High density electronic package comprising stacked sub-modules Tiong C. Go
EP00982671.0	EP	10/16/2000	Highly configurable capacitive transducer interface circuit Christ Ying Hsu
PCT/US87/002746	WO	10/20/1987	High-density electronic modules, process and product Tiong C. Go
EP0385979	EP	10/20/1987	High-density electronic modules, process and product Tiong C. Go
DE0385979	DE	10/20/1987	High-density electronic modules, process and product Tiong C. Go
FR0385979	FR	10/20/1987	High-density electronic modules, process and product Tiong C. Go
60/809,466	US	5/30/2006	Large format thermoelectric infrared detector and a method of fabrication Ying Hsu
GB0385979	GB	10/20/1987	High-density electronic modules, process and product Tiong C. Go

Assignor assigns to Assignee all rights to the inventions, invention disclosures, and discoveries in the assets listed above, together, with the rights, if any, to revive prosecution of claims under such assets and to sue or otherwise enforce any claims under such assets for past, present or future infringement.

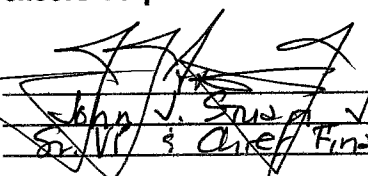
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DATED this 16th day of March 2009.

ASSIGNOR:

Irvine Sensors Corporation

By: 
Name: John V. Sousa Jr.
Title: Sr. VP & Chief Financial Officer

